

Specifications

Insulation Resistance:	1,000MΩ min. at 500V DC
Dielectric Withstanding Voltage:	700V AC for 1 minute
Contact Resistance:	30mΩ max. at 10mA/20mV max.
Current Rating:	1A max.
Operating Temperature Range:	-40°C to +150°C
Mating Cycles:	10,000 insertions min.

Materials and Finish

Housing: Polysulphone (PSF), glass-filled - UL94V-0
 Contacts: Beryllium Copper (BeCu)
 Plating: Gold (0.3μm min.) over Nickel (2.5 to 4.5μm min.)

Features

- ⇨ Dual wipe contacts ensure high reliability
- ⇨ Low costs due to selective gold plating

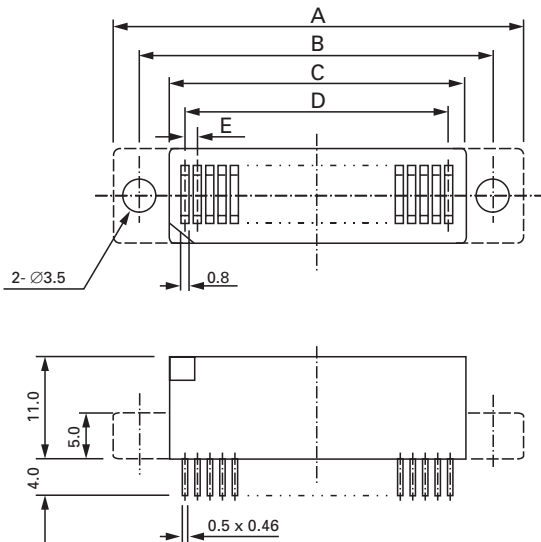


Part Number (Details)

IC70 - 30 11 MF - G 4

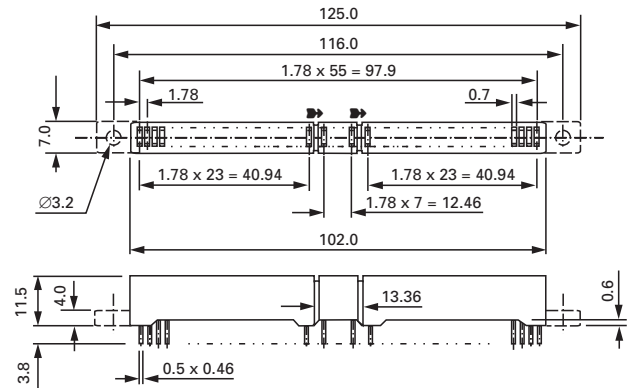
Series No.	IC70
No. of Contact Pins	30
Design Number	11
MF = Flanged Unmarked = Not Flanged	MF
Contact Plating (G = Gold Plating)	G
Straight, Through Hole Type	4

Outline Socket Dimensions

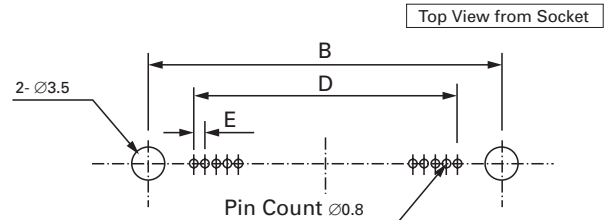


Outline Socket Dimensions for IC70-5616-G4 only ¹⁾

May be cut at points marked by into 3 separate sections



Recommended PC Board Layout



Part Number	Pin Count	A	B	C	D	E
IC70-0726**-G4	7	26.6	19.6	12.6	1.27 x 6 = 7.62	1.27
IC70-1217**-G4	12	41.0	34.0	27.0	2.00 x 11 = 22.00	2.0
IC70-1521**-G4	15	36.8	29.8	22.8	1.27 x 14 = 17.78	1.27
IC70-2020**-G4	20	47.5	40.5	33.5	1.50 x 19 = 28.50	1.5
IC70-2313**-G4	23	44.0	38.0	32.0	1.27 x 22 = 27.94	1.27
IC70-2418**-G4	24	63.0	57.0	51.0	2.00 x 23 = 46.00	2.0
IC70-3011**-G4	30	77.0	67.0	57.0	1.80 x 29 = 52.20	1.8
IC70-3015**-G4	30	57.0	49.0	41.0	1.27 x 29 = 36.83	1.27
IC70-3019**-G4	30	62.5	55.5	48.5	1.50 x 29 = 43.50	1.5
IC70-4014**-G4	40	94.0	84.0	74.0	1.778 x 55 = 69.342	1.778
IC70-5616**-G4 ¹⁾	56	125.0	116.0	102.0	1.78 x 55 = 97.90	1.78